



<b>Title of Change:</b>	New Eutectic solder sphere supplier at bump subcon							
<b>Proposed first ship date:</b>	18 November 2018 or earlier upon customer approval							
<b>Contact information:</b>	Contact your local ON Semiconductor Sales Office or <Erich.Meder@onsemi.com>							
<b>Samples:</b>	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com> (Provide PCN samples prior to Final PCN for all parts with backlog, and affecting customers with Customer Special Requirements. Check with APM for sample size) Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.							
<b>Type of notification:</b>	This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are typically issued 30 days prior to the issuance of the Final Change Notice (FPCN). An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>.							
<b>Change Part Identification:</b>	Can differentiate units with change by date code marking							
<b>Change Category:</b>	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____							
<b>Change Sub-Category(s):</b>	<input type="checkbox"/> Manufacturing Site Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Site Transfer <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Other: _____							
<b>Sites Affected:</b>	ON Semiconductor Sites: None	External Foundry/Subcon Sites: FLIPCHIP INTERNATIONAL INC						
<b>Description and Purpose:</b> FCI's primary sphere supplier is ceasing production of eutectic sphere								
	<table border="1"> <thead> <tr> <th></th> <th>Before Change Description</th> <th>After Change Description</th> </tr> </thead> <tbody> <tr> <td>Eutectic solder sphere</td> <td>Current qualified supplier of Eutectic solder spheres (63Sn / 37Pb)</td> <td>New Metal Industries Eutectic solder spheres 63Sn / 37PB</td> </tr> </tbody> </table>			Before Change Description	After Change Description	Eutectic solder sphere	Current qualified supplier of Eutectic solder spheres (63Sn / 37Pb)	New Metal Industries Eutectic solder spheres 63Sn / 37PB
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Eutectic solder sphere	Current qualified supplier of Eutectic solder spheres (63Sn / 37Pb)	New Metal Industries Eutectic solder spheres 63Sn / 37PB						

**Qualification Plan:**

Wafer level Rel completed

Subcon test vehicle with a 10x10 bump grid

QV Device Name: Eng Substrate

Package: WLCSP

Test	Condition	Interval	Result
High Temperature Storage	150C	1000 hours	0/25
Multiple Reflow	Standard Reflow Conditions	10X reflows	0/25
Auto Clave	121C, 100% RH	48 hours	0/25

**List of Affected Standard Parts:**

Part Number	Qualification Vehicle
20775-001-XDS	20775-001-XDS
21425-001-XDS	21425-001-XDS